

Title (en)
CONNECTION TECHNOLOGY FOR POWER SEMICONDUCTORS COMPRISING A LAYER OF ELECTRICALLY INSULATING MATERIAL THAT
FOLLOWS THE SURFACE CONTOURS

Title (de)
VERBINDUNGSTECHNIK FÜR LEISTUNGSHALBLEITER MIT EINER DER OBERFLÄCHENKONTUR FOLGENDEN SCHICHT AUS
ELEKTRISCH ISOLIERENDEM MATERIAL

Title (fr)
TECHNIQUE DES CONNEXIONS DESTINEE A DES SEMI-CONDUCTEURS DE PUISSANCE ET UTILISANT UNE MATIERE
ELECTRIQUEMENT ISOLANTE QUI SUIV LES CONTOURS DE SURFACE

Publication
EP 1597757 A2 20051123 (DE)

Application
EP 04705063 A 20040126

Priority
• EP 2004000629 W 20040126
• DE 10308978 A 20030228

Abstract (en)
[origin: WO2004077548A2] A layer of electrically insulating material is applied to a substrate and a component located thereon, in such a way that
said layer follows the surface contours.

IPC 1-7
H01L 21/60

IPC 8 full level
H01L 21/60 (2006.01); **H01L 23/538** (2006.01); **H01L 25/07** (2006.01)

CPC (source: EP US)
H01L 23/5389 (2013.01 - EP US); **H01L 24/24** (2013.01 - EP US); **H01L 24/82** (2013.01 - EP US); **H01L 25/072** (2013.01 - EP US);
H01L 2224/2402 (2013.01 - EP US); **H01L 2224/24051** (2013.01 - EP US); **H01L 2224/24225** (2013.01 - EP US);
H01L 2224/24226 (2013.01 - EP US); **H01L 2224/45015** (2013.01 - EP US); **H01L 2224/45124** (2013.01 - EP US);
H01L 2924/00011 (2013.01 - EP US); **H01L 2924/00014** (2013.01 - EP US); **H01L 2924/01005** (2013.01 - EP US);
H01L 2924/01006 (2013.01 - EP US); **H01L 2924/01013** (2013.01 - EP US); **H01L 2924/0102** (2013.01 - EP US);
H01L 2924/01027 (2013.01 - EP US); **H01L 2924/01029** (2013.01 - EP US); **H01L 2924/01033** (2013.01 - EP US);
H01L 2924/01058 (2013.01 - EP US); **H01L 2924/01074** (2013.01 - EP US); **H01L 2924/01078** (2013.01 - EP US);
H01L 2924/01079 (2013.01 - EP US); **H01L 2924/01082** (2013.01 - EP US); **H01L 2924/01327** (2013.01 - EP US);
H01L 2924/014 (2013.01 - EP US); **H01L 2924/09701** (2013.01 - EP US); **H01L 2924/15787** (2013.01 - EP US);
H01L 2924/19043 (2013.01 - EP US); **H01L 2924/30107** (2013.01 - EP US); **H01L 2924/3025** (2013.01 - EP US)

Citation (search report)
See references of WO 2004077548A2

Citation (examination)
• JP H07193174 A 19950728 - MITSUBISHI ELECTRIC CORP
• EP 0747949 A2 19961211 - MOTOROLA INC [US]
• US 3099608 A 19630730 - RADOVSKY DAVID A, et al

Designated contracting state (EPC)
DE FR GB SE

DOCDB simple family (publication)
WO 2004077548 A2 20040910; WO 2004077548 A3 20050512; CN 100499053 C 20090610; CN 1757103 A 20060405;
EP 1597757 A2 20051123; JP 2006514785 A 20060511; JP 4763463 B2 20110831; US 2006192290 A1 20060831;
US 2007216025 A1 20070920; US 7208347 B2 20070424; US 7855451 B2 20101221

DOCDB simple family (application)
EP 2004000629 W 20040126; CN 200480005533 A 20040126; EP 04705063 A 20040126; JP 2005518649 A 20040126;
US 54717304 A 20040126; US 72890007 A 20070327